



# NEC's 1/4 W SINGLE CONTROL L, S-BAND SPDT SWITCH

## UPG2012TK

### FEATURES

- **SUPPLY VOLTAGE:**  
 $V_{DD} = 2.7$  to  $3.0$  V (2.8 V TYP.)
- **SINGLE SWITCH CONTROL VOLTAGE:**  
 $V_{cont} (H) = 2.7$  to  $3.0$  V (2.8 V TYP.)  
 $V_{cont} (L) = -0.2$  to  $+0.2$  V (0 V TYP.)
- **LOW INSERTION LOSS:**  
 $L_{INS1} = 0.27$  dB TYP. @  $f = 0.5$  to  $1.0$  GHz,  $V_{DD} = 2.8$  V,  $V_{cont} = 2.8$  V/0 V  
 $L_{INS2} = 0.30$  dB TYP. @  $f = 2.0$  GHz,  $V_{DD} = 2.8$  V,  $V_{cont} = 2.8$  V/0 V  
 $L_{INS3} = 0.30$  dB TYP. @  $f = 2.5$  GHz,  $V_{DD} = 2.8$  V,  $V_{cont} = 2.8$  V/0 V  
(Reference value)
- **HIGH ISOLATION:**  
 $ISL1 = 30$  dB TYP. @  $f = 0.5$  to  $2.0$  GHz,  $V_{DD} = 2.8$  V,  $V_{cont} = 2.8$  V/0 V  
 $ISL2 = 30$  dB TYP. @  $f = 2.5$  GHz,  $V_{DD} = 2.8$  V,  $V_{cont} = 2.8$  V/0 V  
(Reference value)
- **HIGH-DENSITY SURFACE MOUNTING:**  
6-pin lead-less minimold package

### DESCRIPTION

NEC's UPG2012TK is a single control GaAs MMIC for L, S-band SPDT (Single Pole Double Throw) switch for mobile phone and L, S-band applications.

This device can operate frequency from 0.5 GHz to 2.5 GHz, with low insertion loss and high isolation.

This device is housed in a 6-pin lead-less minimold package suitable for high-density surface mounting.

### APPLICATIONS

- L, S-band digital cellular or cordless handsets
- Bluetooth™, W-LAN and WLL
- Short Range Wireless

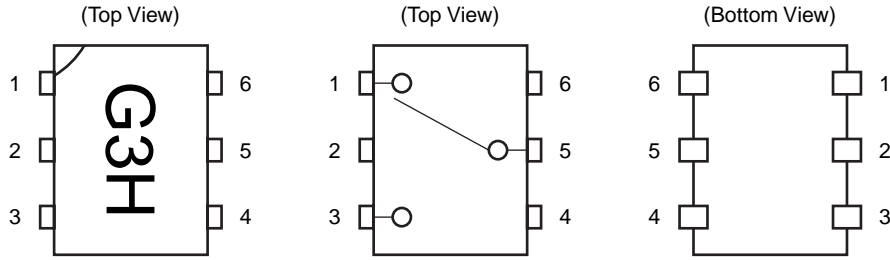
### ORDERING INFORMATION

Part Number	Package	Marking	Supplying Form
UPG2012TK-E2	6-pin lead-less minimold (1511)	G3H	<ul style="list-style-type: none"><li>• Embossed tape 8 mm wide</li><li>• Pin 1, 6 face the perforation side of the tape</li><li>• Qty 5 kpcs/reel</li></ul>

**Remark** To order evaluation samples, contact your nearby sales office.  
Part number for sample order: UPG2012TK

**Caution** Observe precautions when handling because these devices are sensitive to electrostatic discharge.

**PIN CONNECTIONS**



Pin No.	Pin Name
1	OUTPUT1
2	GND
3	OUTPUT2
4	V <sub>cont</sub>
5	INPUT
6	V <sub>DD</sub>

**TRUTH TABLE**

V <sub>cont</sub>	INPUT-OUTPUT1	INPUT-OUTPUT2
Low	OFF	ON
High	ON	OFF

**ABSOLUTE MAXIMUM RATINGS** (T<sub>A</sub> = 25°C, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Supply Voltage	V <sub>DD</sub>	+6.0	V
Switch Control Voltage	V <sub>cont</sub>	+6.0	V
Input Power	P <sub>in</sub>	+26	dBm
Power Dissipation	P <sub>D</sub>	150 <b>Note</b>	mW
Operating Ambient Temperature	T <sub>A</sub>	-45 to +85	°C
Storage Temperature	T <sub>stg</sub>	-55 to +150	°C

**Note** Mounted on double-sided copper-clad 50 × 50 × 1.6 mm epoxy glass PWB, T<sub>A</sub> = +85°C

**RECOMMENDED OPERATING RANGE** (T<sub>A</sub> = 25°C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage	V <sub>DD</sub>	2.7	2.8	3.0	V
Switch Control Voltage (H)	V <sub>cont(H)</sub>	2.7	2.8	3.0	V
Switch Control Voltage (L)	V <sub>cont(L)</sub>	-0.2	0	0.2	V

## ELECTRICAL CHARACTERISTICS

(TA = +25°C, VDD = 2.8 V, Vcont = 2.8 V/0 V, DC blocking capacitors = 56 pF, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Insertion Loss1	LINS1	f = 0.5 to 1.0 GHz	-	0.27	0.50	dB
Insertion Loss2	LINS2	f = 2.0 GHz	-	0.30	0.50	dB
Isolation1	ISL1	f = 0.5 to 2.0 GHz	24	30	-	dB
Input Return Loss	RLin	f = 0.5 to 2.5 GHz	15	20	-	dB
Output Return Loss	RLout	f = 0.5 to 2.5 GHz	15	20	-	dB
0.1 dB Gain Compression Input Power <b>Note</b>	P <sub>in(0.1 dB)</sub>	f = 2.0 GHz	+17.5	+20.5	-	dBm
Supply Current	I <sub>DD</sub>		-	50	100	□A
Switching Control Current	I <sub>cont</sub>		-	4	20	□A

**Note** P<sub>in</sub> (0.1 dB) is the measured input power level when the insertion loss increases 0.1 dB more than that of linear range.

## STANDARD CHARACTERISTICS FOR REFERENCE

(TA = +25°C, VDD = 2.8 V, Vcont = 2.8 V/0 V, DC blocking capacitors = 56 pF, unless otherwise specified)

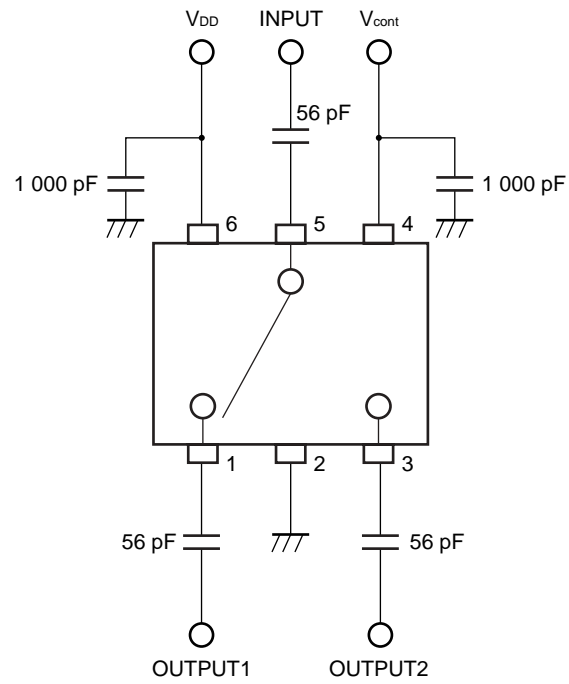
Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Insertion Loss3	LINS3	f = 2.5 GHz	-	0.30	-	dB
Isolation2	ISL2	f = 2.5 GHz	-	30	-	dB
1 dB Gain Compression Input Power <b>Note</b>	P <sub>in(1 dB)</sub>	f = 2.0 GHz	-	+24.0	-	dBm
Switching Control Speed	t <sub>SW</sub>		-	300	-	ns

**Note** P<sub>in</sub> (1dB) is the measured input power level when the insertion loss increases 1 dB more than that of linear range.

**Caution** It is necessary to use DC blocking capacitors with the device.  
The value of DC blocking capacitors should be chosen to accommodate the frequency of operation, bandwidth, switching speed and the condition with the actual board of the system. The range of recommended DC blocking capacitor value is less than 100 pF.

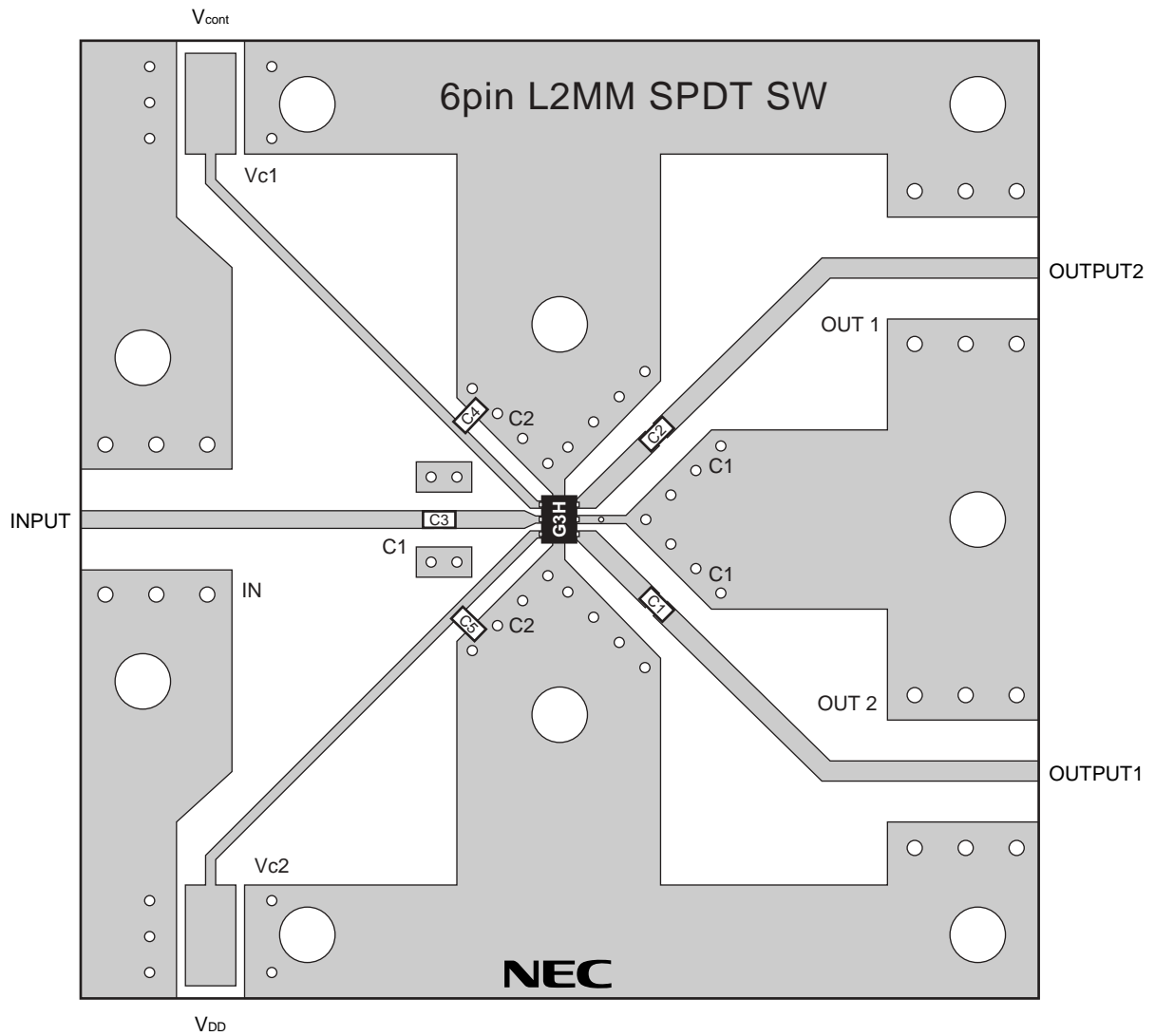
**EVALUATION CIRCUIT**

( $V_{DD} = 2.8\text{ V}$ ,  $V_{cont} = 2.8\text{ V}/0\text{ V}$ , DC blocking capacitors =  $56\text{ pF}$ )



The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

ILLUSTRATION OF THE TEST CIRCUIT ASSEMBLED ON EVALUATION BOARD

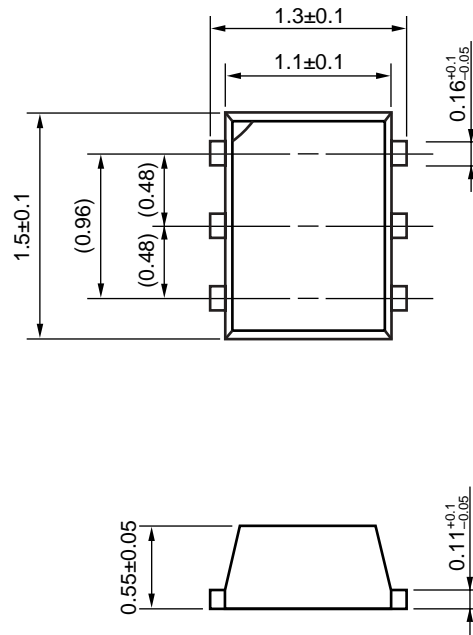


USING THE NEC EVALUATION BOARD

Symbol	Values
C1, C2, C3	56 pF
C4, C5	1 000 pF

**PACKAGE DIMENSIONS**

6-PIN LEAD-LESS MINIMOLD (1511) (UNIT: mm)

**Remark ( ):** Reference value

**RECOMMENDED SOLDERING CONDITIONS**

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions	Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) : 260°C or below Time at peak temperature : 10 seconds or less Time at temperature of 220°C or higher : 60 seconds or less Preheating time at 120 to 180°C : 120±30 seconds Maximum number of reflow processes : 3 times Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	IR260
VPS	Peak temperature (package surface temperature) : 215°C or below Time at temperature of 200°C or higher : 25 to 40 seconds Preheating time at 120 to 150°C : 30 to 60 seconds Maximum number of reflow processes : 3 times Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	VP215
Wave Soldering	Peak temperature (molten solder temperature) : 260°C or below Time at peak temperature : 10 seconds or less Preheating temperature (package surface temperature) : 120°C or below Maximum number of flow processes : 1 time Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (pin temperature) : 350°C or below Soldering time (per side of device) : 3 seconds or less Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	HS350

**Caution Do not use different soldering methods together (except for partial heating).**

Life Support Applications

These NEC products are not intended for use in life support devices, appliances, or systems where the malfunction of these products can reasonably be expected to result in personal injury. The customers of CEL using or selling these products for use in such applications do so at their own risk and agree to fully indemnify CEL for all damages resulting from such improper use or sale.

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